



IR-1773 (2-2498)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Patent Application of

Mark Pavier

Date: January 22, 2001

Serial No. 09/718,932

Group Art Unit:

Filed: November 22, 2000

Examiner:

For: **POWER SEMICONDUCTOR DIE ATTACH PROCESS USING
CONDUCTIVE ADHESIVE FILM**

Asst. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

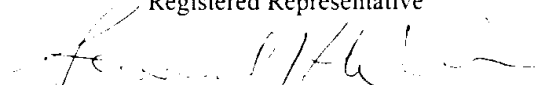
REQUEST FOR APPROVAL OF DRAWING CORRECTIONS

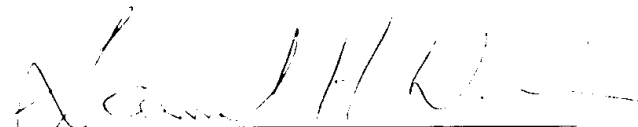
Sir:

You are advised that, subject to the approval of the Patent Examiner, applicant proposes to amend drawing Fig. 5 as indicated in red on the enclosed photocopy.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on January 22, 2001

Respectfully submitted,

Samuel H. Weiner
Name of applicant, assignee or
Registered Representative

Signature
January 22, 2001
Date of Signature


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SHW:gl